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3D Semiconductor Packaging Market - Forecasts from 2019 to 2024

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Abstracts

The three-dimensional integrated circuits (ICs) are integrated circuits manufactured using a new packaging technology of stacking silicon wafers and interconnecting them vertically using Through Silicon Vias (TSVs) or Cu-Cu connections, so that they behave as a single device, achieving improved performance at reduced power and smaller footprint than two-dimensional processes. The 3D semiconductor packaging market is expected to grow at a significant CAGR of 14.46% to reach a market size of US$6.044 billion in 2024 from US$2.688 billion in 2018. As the demand for higher capacity electronic devices with more efficient power consumption increases, it drives the need to implement 3D ICs in various such devices.

DRIVERS

Increasing global demand for high-end electronic devices using miniaturized circuits with low power consumption and reduced size.

Heavy investments on the R&D by many key industry players.

RESTRAINTS

Competition from already established tech giants who are heavily investing in this area.

Lack of clarity regarding standardization and ownership concerns

RECENT DEVELOPMENTS

In 2015, Jiangsu Chanjiang Electronics Technology Co. Ltd acquired Statschippac to

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augment its R&D capabilities.

ASE Group is considering a merger with SPIL.

Segmentation

The 3D Semiconductor packaging market has been analyzed through the following segments:

By Technology

Through Silicon Vias (TSV)

Fan Out Wafer Level Packaging

Wire Bonding

Others

By Industry Vertical

Electronics

Communication and Technology

Manufacturing

Automotive

Defense and Aerospace

Healthcare

Others

By Material

Bonding Wire

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Lead frame

Organic Substrate

Encapsulation Resin

Ceramic Package

Die Attach Material

Others

By Geography

North America

USA

Canada

Others

South America

Brazil

Argentina

Others

Europe

United Kingdom

Germany

France

Others

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Middle East and Africa

Israel

UAE

Saudi Arabia

Others

Asia Pacific

China

Japan

South Korea

India

Others

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